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USPC **349/58**

(57) **ABSTRACT**

A display device according to an embodiment includes a liquid crystal panel; a backlight assembly disposed below the liquid crystal panel; a chassis including: a first support section, which is disposed at sides of the liquid crystal panel and the backlight assembly, and a second support section, which is bent or curved from the first support section; and a frame disposed at an inner side of the chassis, wherein the frame has a first frame, a second frame, a third frame and a fourth frame and at least one of the first to the fourth frames has a height lower than a height of the first support section.

7 Claims, 9 Drawing Sheets

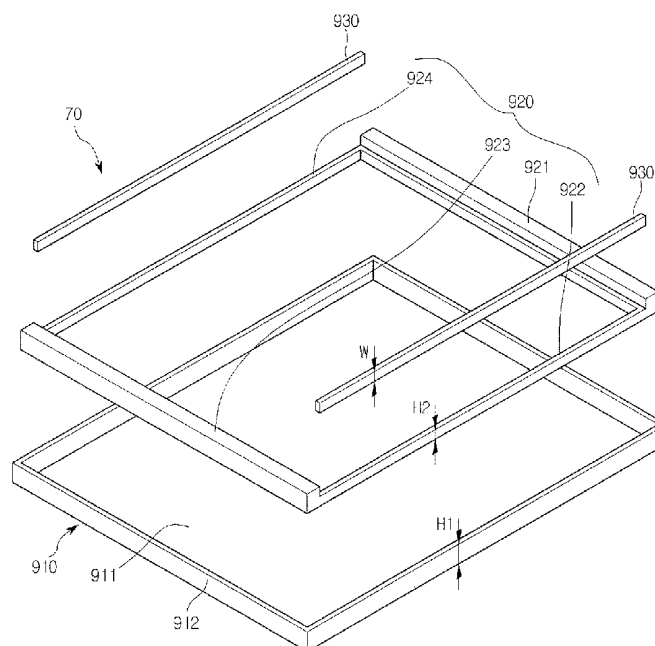
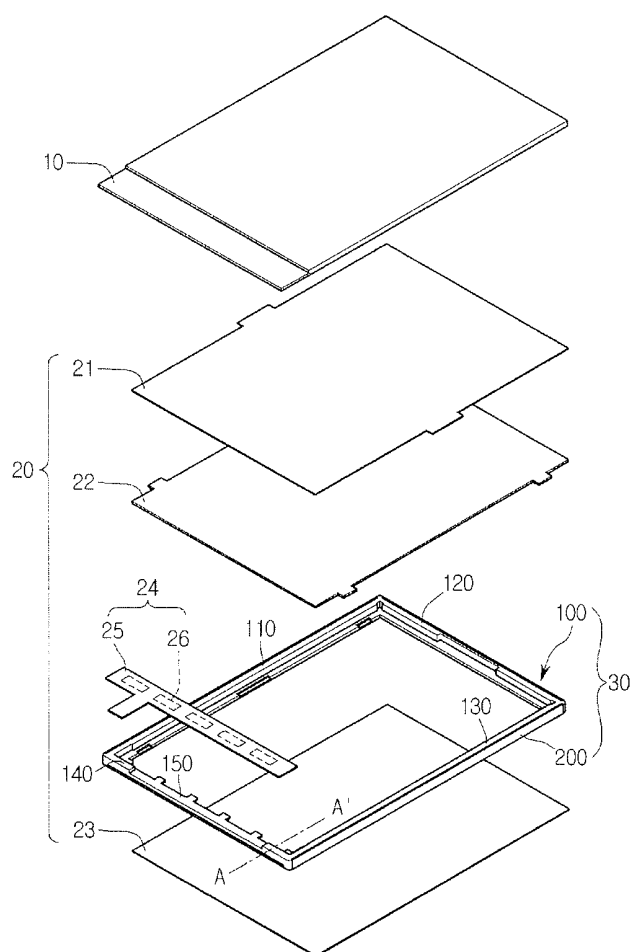


Fig. 1



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DISPLAY DEVICE

CROSS REFERENCE TO RELATED APPLICATIONS

This application is a Divisional of copending application Ser. No. 12/666,982 filed on Dec. 28, 2009, which is a National Phase of PCT International Application No. PCT/KR2008/003877 filed on Jul. 1, 2008, which claims the benefit of Korean Patent Application Nos. 10-2007-0067994 filed on Jul. 6, 2007, 10-2007-0069895 filed on Jul. 12, 2007, and 10-2007-0072680 filed on Jul. 20, 2007. The entire contents of all of the above applications are hereby incorporated by reference.

TECHNICAL FIELD

The embodiment relates to a display device.

BACKGROUND ART

An LCD (liquid crystal display device) displays an image using electrical and optical characteristics of liquid crystal. Since the LCD is a non-emissible device, the LCD requires a backlight assembly. A receiving device is required, which receives a liquid crystal panel or the backlight assembly and comprises a mold frame and a chassis.

The mold frame receives and fixes a backlight unit and an LCD panel. The chassis is coupled with the mold frame to reinforce the strength of the backlight unit, and has a structure corresponding to the external appearance of the mold frame.

Thus, the mold frame and the chassis are manufactured, respectively, and then are fitted with each other.

DISCLOSURE OF INVENTION

Technical Problem

The embodiment provides a display device having improved strength.

Technical Solution

The display device according to an embodiment comprises a liquid crystal panel; a backlight assembly disposed below the liquid crystal panel; a frame receiving at least a part of the liquid crystal panel and the backlight assembly; and a chassis disposed at the frame, wherein at least a part of the chassis is inserted into the frame.

The display device according to another embodiment comprises a liquid crystal panel; a first support section disposed below the liquid crystal panel; and a second support section connected with the first support section, and disposed at a side of the liquid crystal panel while exposing corners of the liquid crystal panel.

The display device according to further another embodiment comprises a liquid crystal panel; a backlight assembly disposed below the liquid crystal panel; a chassis comprising a first support section, which is disposed at sides of the liquid crystal panel and the backlight assembly, and a second support section is bent or curved from the first support section; and a frame disposed at an inner side of the chassis, wherein at least a part of the frame has a height lower than a height of the first support section.

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Advantageous Effects

According to the embodiment, the structure of the display device is modified such that the display device has improved strength as well as a slim size.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is an exploded perspective view illustrating an LCD according to a first embodiment;

FIG. 2 is a perspective view illustrating a state in which a mold frame is separated from a chassis;

FIG. 3 is a sectional view taken along line A-A of FIG. 1;

FIG. 4 is a sectional view illustrating a method in which a mold frame is coupled with a chassis;

FIG. 5 is a perspective view illustrating a state in which a mold frame is coupled with a chassis according to a second embodiment;

FIG. 6 is a sectional view taken along line B-B of FIG. 5;

FIG. 7 is a plan view illustrating a chassis coupled with a lamp receiving section of a mold frame;

FIG. 8 is a perspective view illustrating a receiving device according to a third embodiment;

FIG. 9 is a perspective view illustrating a state in which a liquid crystal panel is coupled with the receiving device of FIG. 8;

FIG. 10 is an enlarged plan view illustrating the area C of FIG. 9;

FIG. 11 is a perspective view illustrating a state in which a liquid crystal panel is coupled with a receiving device according to a fourth embodiment;

FIG. 12 is an enlarged plan view illustrating the area D of FIG. 11;

FIG. 13 is a perspective view illustrating a state in which a liquid crystal panel is coupled with a chassis according to a fifth embodiment;

FIG. 14 is an enlarged plan view illustrating the area E of FIG. 13;

FIG. 15 is a perspective view illustrating a state in which a liquid crystal panel is coupled with a chassis according to a sixth embodiment;

FIG. 16 is an enlarged plan view illustrating the area F of FIG. 15;

FIG. 17 is an exploded perspective view illustrating a receiving device according to a seventh embodiment;

FIG. 18 is a plan view illustrating an LCD according to a seventh embodiment;

FIG. 19 is a sectional view taken along line G-G of FIG. 18;

FIG. 20 is a plan view illustrating an LCD according to an eighth embodiment; and

FIG. 21 is a sectional view taken along line I-I of FIG. 20.

BEST MODE FOR CARRYING OUT THE INVENTION

Hereinafter, an LCD and a manufacturing method thereof according to embodiments will be described with reference to the accompanying drawings.

FIG. 1 is an exploded perspective view illustrating an LCD according to a first embodiment.

Referring to FIG. 1, the LCD comprises a liquid crystal panel 10, a backlight assembly 20 and a receiving device 30.

The liquid crystal panel 10 includes a TFT substrate, a color filter substrate and a liquid crystal layer interposed between the TFT substrate and the color filter substrate.

The backlight assembly **20** comprises a light emitting unit **24**, a light guide plate **22**, an optical sheet **21** and a reflective sheet **23**.

The light emitting unit **24** comprises a FPCB (flexible printed circuit board) **25** and a lamp **26** such as an LED or a CCFL mounted on the FPCB **25**. The lamp **26** comprising a plurality of LEDs is mounted on the rear surface of the FPCB **25** of the light emitting unit **24** while being electrically connected with a main substrate (not shown).

The light guide plate **22** receives light from the light emitting unit **24** to uniformly distribute the light over the whole light emitting area of a backlight.

The optical sheet **21** is attached to the light guide plate **22** and selectively comprises a lens sheet, a diffusion sheet, a protective sheet and the like.

The reflective sheet **23** is attached to the bottom surface of the light guide plate **22** to reflect light, which is leaked through the bottom surface of the light guide plate **22**, to the light emitting area.

The liquid crystal panel **10** and the backlight assembly **20** must be received and fixed. To this end, the receiving device **30** is required.

FIG. 2 is a perspective view illustrating a state in which a mold frame is separated from a chassis and FIG. 3 is a sectional view taken along line A-A of FIG. 1.

Referring to FIG. 2, the receiving device **30** comprises the mold frame **100** and the chassis **200**.

The mold frame **100** has a shape corresponding to the external appearance of the liquid crystal panel **10** and the backlight assembly **20** such that the liquid crystal panel **10** and the backlight assembly **20** can be received in the mold frame **100**.

The mold frame **100**, for example, comprises four frames. Hereinafter, the four frames will be referred to as a first frame **110**, a second frame **120**, a third frame **130** and a fourth frame **140**.

The first frame **110** faces the third frame **130** and the second frame **120** faces the fourth frame **140**. The first to fourth frames **110**, **120**, **130** and **140** are interconnected to form a closed loop. When viewed in a plan view, the first to fourth frames **110**, **120**, **130** and **140** form a rectangular frame.

For example, the mold frame **100** may comprise synthetic resin such as polycarbonate resin, styrene resin, polyvinyl chloride or polypropylene.

A lamp receiving section **150** can be formed at the inner side of the fourth frame **140** to receive the light emitting unit **24**.

The lamp receiving section **150** comprises a lamp receiving groove **151**, which receives the lamp **26**, and a support **153** that receives the FPCB **25** on which the lamp **26** is mounted.

The lamp receiving section **150** has a thickness thinner than that of the fourth frame **140** such that the light emitting unit **24** can be received in the lamp receiving section **150**.

The lamp receiving section **150** has a thickness T2 thinner than a thickness T1 of an end portion of the fourth frame **140**, so that a step difference is formed between the end portion of the fourth frame **140** and the lamp receiving section **150**.

As the light emitting unit **24** is received in the lamp receiving section **150**, the lamp **26** of the light emitting unit **24** is inserted into the lamp receiving groove **151** and the FPCB **25** is installed at the support **153**.

Thus, although the light emitting unit **24** is received in the lamp receiving section **150** having the thickness thinner than that of the end portion of the fourth frame **140**, the entire thickness of the LCD is not affected by the step difference

formed between the end portion of the fourth frame **140** and the lamp receiving section **150**, so that the LCD can have a slim structure.

The chassis **200** is coupled with the outer end surface of the mold frame **100** to reinforce the strength of the mold frame **100**.

The chassis **200** surrounds the first to fourth frames **110**, **120**, **130** and **140**.

The chassis **200**, for example, comprises four frames. Hereinafter, the four frames will be referred to as a fifth frame **210**, a sixth frame **220**, a seventh frame **230** and an eighth frame **240**.

The chassis **200** may comprise metal material. For example, the chassis **200** may comprise at least one of stainless steel, iron, aluminum, an aluminum alloy and copper.

The fifth to seventh frames **210**, **220** and **230** are coupled with the first to third frames **110**, **120** and **130**, respectively, and the eighth frame **240** is coupled with the fourth frame **140**.

The fifth to seventh frames **210**, **220** and **230** comprise a first support section **211**, a second support section **212** and a third support section **213**, respectively.

The first support section **211** is disposed below the mold frame **100**. In more detail, the first support section **211** is coupled with the bottom surfaces of the first to third frames **110**, **120** and **130**. Further, the first support section **211** supports the mold frame **100**.

The second support section **212** is extended in vertical direction with the first support section **211** from the first support section **211** upward. The second support section **212** is disposed at the outer side of the mold frame **100**. In more detail, the second support section **212** is coupled with the outer sides of the first to third frames **110**, **120** and **130**.

The third support section **213** is extended in vertical direction with and from the second support section **212**. The third support section **213** is disposed above the mold frame **100**. In more detail, the third support section **213** is coupled with the upper surfaces of the first to third frames **110**, **120** and **130**.

That is, the fifth to seventh frames **210**, **220** and **230** of the chassis **200** may have a substantially C-shaped section made of the first to third support sections **211** to **213**, respectively.

Referring to FIGS. 2 and 3, the eighth frame **240** comprises the first support section **211** coupled with the bottom surface of the fourth frame **140**, and a fourth support section **214** inserted into the fourth frame **140** of the mold frame **100**.

Although not shown in FIGS. 2 and 3, the fifth to seventh frames **210**, **220** and **230** of the chassis **200** may have the same structure as that of the eighth frame **240** of the chassis **200**.

The fourth support section **214** is bent or curved by 180° from the end portion of the first support section **211** and is extended from the first support section **211** such that the first support section **211** is parallel to the fourth support section **214**. That is, the first support section **211** and the fourth support section **214** of the eighth frame **240** form a folding structure such that the first support section **211** faces the fourth support section **214**.

Thus, the first support section **211** of the eighth frame **240** of the chassis **200** is coupled with the bottom surface of the fourth frame **140** of the mold frame **100**, and the fourth support section **214** is inserted into the fourth frame **140**.

As the chassis **200** is coupled with the mold frame **100**, the first to third frames **210**, **220** and **230** of the chassis **200** surround the outer end surfaces of the first to third frames **110**, **120** and **130** of the mold frame **100**.

Further, the first support section **211** of the eighth frame **240** is coupled with the bottom surface of the fourth frame **140**, and the fourth support section **214** is inserted into the

fourth frame **140**, so that the strength of the mold frame **100** can be enhanced without exerting an influence upon the thickness of the mold frame **100**.

Thus, the fourth support section **214** is coupled with the fourth frame **140** in the state in which the fourth support section **214** is bent or curved by 180° from the first support section **211**, the fourth support section **214** can also be coupled with the lamp support **153** having a thin thickness **T2** of the fourth frame **140**.

In an area of a chassis where the hamming is not conventionally available due to the restriction rule for a bending process, the embodiment enables the hamming, so that the efficiency of the chassis can be improved even if the chassis has a thin thickness. Further, when the chassis **200** is folded by bending the chassis at an angle of 180, a physical space actually exists, so that the mold frame **100** can be firmly coupled with the chassis **200** during an insert injection molding process.

Furthermore, when the chassis **200** is folded by bending the chassis **200** at an angle of 180, a coupling space with the mold frame **100** exists, so that the strength of the mold frame **100** can be enhanced.

Although no coupling space with the mold frame **100** exists because the first and fourth support sections **211** and **214** of the chassis **200** closely make contact with each other, the fourth support section **214** of the chassis **200** supports the mold frame **100**, so that the strength of the mold frame **100** can be enhanced.

The chassis **200** is coupled with the first to third frames **110**, **120** and **130** of the mold frame **100** in the form of a substantial C shape, so that the strength of the mold frame **100** can be reinforced.

Further, the chassis **200** is inserted into the fourth frame **140** having a thin thickness, so that the strength of the mold frame **100** can be considerably reinforced.

The mold frame **100** can be coupled with the chassis **200** through insert injection molding process.

FIG. **4** is a sectional view illustrating a method in which the mold frame is coupled with the chassis.

Referring to FIG. **4**, according to the insert injection molding process, the chassis **200** comprising the fifth to eighth frames **210**, **220**, **230** and **240** is installed at a mold frame **40** of an injection molding apparatus (not shown). In particular, FIG. **4** is a sectional view of the mold frame **40** at which the eighth frame **240** of the chassis **200** is installed.

The reference number **50** indicates a material injector.

The first and fourth support sections **211** and **214** of the eighth frame **240** can be formed through a hamming process. For example, the first support section **211** can face the fourth support section **214** by bending, which extends from the end portion of the first support section **211** of the eighth frame **240**, at an angle of 180.

Then, the injection molding process, in which synthetic resin (material of the mold frame **100**) is injected into the frame **40** for molding and is heated and cured, is performed, so that the chassis **200** can be integrally formed with the mold frame **100**.

Thus, the chassis **200** is coupled with the mold frame **100** through the injection molding process, so that the coupling strength therebetween can be enhanced.

At this time, when the first and fourth support sections **211** and **214** of the chassis **200** face each other, a physical space exists between the first and fourth support sections **211** and **214**.

Further, mold material is also inserted between the first and fourth support sections **211** and **214** and the mold frame **100**

is firmly fixed to the chassis **200**, so that the coupling strength between the first and fourth support sections **211** and **214** can be increased.

Moreover, the first and fourth support sections **211** and **214** of the chassis **200** has a folding structure through the hamming process, so that the hamming process can be applied to the mold frame **100** requiring thin thickness. Thus, the LCD can have a slim structure.

FIG. **5** is a perspective view illustrating a state in which a mold frame is coupled with a chassis according to a second embodiment, FIG. **6** is a sectional view taken along line B-B of FIG. **5**, and FIG. **7** is a plan view illustrating the chassis coupled with a lamp receiving section of the mold frame.

Referring to FIGS. **5** and **6**, the chassis **300** has a shape corresponding to the external appearance of the mold frame **100** shown in FIG. **2** to surround the first to fourth frames **110**, **120**, **130** and **140** of the mold frame **100**.

The chassis **300**, for example, comprises four frames formed in one united body.

The chassis **300** may comprise metal material. For example, the chassis **300** may comprise at least one of stainless steel, iron, aluminum, an aluminum alloy and copper.

The chassis **300** comprises a first support section **311**, a second support section **312** and a fourth support section **314**.

The first support section **311** is disposed below the mold frame **100** to support the mold frame **100**. In more detail, the first support section **311** is coupled with the bottom surface of the mold frame **100**.

The second support section **312** extends from the end portion of the first support section **311** and then is extended in vertical direction with the first support section **311** such that the second support section **312** is coupled with the outer side of the mold frame **100**.

The fourth support section **314** extends from the end portion of the second support section **312** and then is extended in horizontal direction with the second support section **312** such that the fourth support section **314** is inserted into the mold frame **100**.

That is, the first support section **311** is connected in parallel with the fourth support section **314** through the second support section **312** while facing the fourth support section **314**.

The chassis **300** has a substantially C-shaped section made of the first support section **311**, the second support section **312** and the fourth support section **314**. In particular, the chassis **300** has a thickness **T4** thinner than the thickness **T3** of the mold frame **100**, so that the chassis **300** can be inserted into the mold frame **100**.

As the chassis **300** is coupled with the mold frame **100**, the first support section **311** is coupled with the bottom surfaces of the first to fourth frames **110**, **120**, **130** and **140** of the mold frame **100**.

Further, the second support section **312** is coupled with the outer sides of the first to fourth frames **110**, **120**, **130** and **140**, and the fourth support section **314** is inserted into outer sides of the first to fourth frames **110**, **120**, **130** and **140**.

Although not shown in FIGS. **5** and **6**, the fifth to seventh frames **310**, **320** and **330** of the chassis **300** have the same structure as that of the fifth to seventh frames **210**, **220** and **230** of the chassis **200** of FIG. **2** to surround the first to third frames **110**, **120** and **130** of the mold frame **100**, respectively.

Referring to FIG. **7**, the chassis **300** coupled with the fourth frame **140** of the mold frame **100** may be selectively exposed.

The lamp receiving section **150** is formed in the fourth frame **140**, so that a step difference is formed between the fourth frame **140** and the lamp receiving section **150**. Thus,

the upper surface of the fourth support section **314** of the chassis **300** coupled with the lamp receiving section **150** can be exposed.

That is, the fourth support section **314** of the chassis **300** is extended from the end of the second support section **312** in horizontal direction on the height of the thickness of the lamp receiving section **150**.

At this time, since the end portion of the fourth frame **140** of the mold frame **100** has a thickness thicker than that of the lamp receiving section **150**, a portion of the chassis **300** is inserted into the fourth frame **140** in the end portion of the fourth frame **140** and the remaining portion of the chassis **300** is positioned at the upper portion of the lamp receiving section **150** while being exposed to the outside.

Further, the second support section **312** of the chassis **300** and the lamp receiving section **150** can have the same surface height.

Since the thickness **T4** of the second support section **312** of the chassis **300** is equal to the thickness **T3** of the lamp receiving section **150**, the fourth support section **314** extending from the second support section **312** can be located on the same plane with the lamp receiving section **150**.

Thus, if the light emitting unit **24** is located at the upper portion of the lamp receiving section **150** and the fourth support section **314**, which have the flat structure, the FPCB **25** also maintains flatness without protruding.

This can be achieved using the insert injection molding process as mentioned above.

Further, since the chassis **300** has a structure designed to surround the first to fourth frames **110**, **120**, **130** and **140** of the mold frame **100**, in particular, the lamp receiving section **150** having a thin thickness, the chassis **300** can uniformly support the whole area of the mold frame **100**, so that the strength of the mold frame **100** can be improved.

Furthermore, the contact area between the substantial C-shaped chassis **300** and the mold frame **100** is increased, so that the strength of the mold frame **100** can be reinforced.

According to the related art, although the mold frame is coupled with the chassis in an area in which the FPCB and the LED FPCB of the LCD are installed, the strength of the mold frame is slightly improved due to the step difference between the mold frame and the chassis.

However, the embodiment uses the structure and the method in which the chassis is inserted into the mold frame to remove the step difference between the mold frame and the chassis, so that the strength of the chassis can be significantly improved. In detail, the embodiment uses the insert molding structure to improve the strength of the chassis. In addition, the chassis can be formed with the substantially C-shaped structure through hamming and the step difference can be removed between the mold frame and the chassis, so that the strength of the chassis can be significantly improved.

Further, many limitations exist when performing hamming to make the substantial C-shaped chassis. However, according to the embodiment, the bending height of the substantial C-shaped chassis can be properly lowered within the limitations, so that the mold frame can be fabricated with a predetermined shape.

In particular, the hamming conditions for the substantial C-shaped chassis are adjusted such that the hamming can be available in various places in the chassis. Thus, the strength of the chassis is significantly improved.

Moreover, the thickness of the mold frame is decreased using the hamming process for the substantial C-shaped chassis, so that the receiving device can have a slim structure.

Hereinafter, a receiving device according to a third embodiment will be described with reference to FIGS. **8** to **10**.

FIG. **8** is a perspective view illustrating the receiving device according to the third embodiment, FIG. **9** is a perspective view illustrating a state in which a liquid crystal panel is coupled with the receiving device of FIG. **8**, and FIG. **10** is an enlarged plan view illustrating the area C of FIG. **9**.

Referring to FIGS. **8** to **10**, the LCD comprises a liquid crystal panel **10**, and a receiving device **60**.

The liquid crystal panel **10** includes upper and lower transparent substrates, and a liquid crystal layer interposed between the upper and lower transparent substrates. At least one liquid crystal panel **10** is prepared according to the number of displayed screens.

The receiving device **60** receives the liquid crystal panel **10**. Further, a backlight assembly that irradiates light toward the liquid crystal panel **10** is disposed below the liquid crystal panel **10**. The receiving device **60** can receive the liquid crystal panel **10** and the backlight assembly.

The receiving device **60** comprises a mold frame **400** and a chassis **500**.

The mold frame **400** has a shape corresponding to the external appearance of the liquid crystal panel **10** to receive the liquid crystal panel **10**.

The mold frame **400** comprises a first mold frame **401** and a second mold frame **402** to protect the side of the liquid crystal panel **10**. For example, the mold frame **400** may comprise synthetic resin such as polycarbonate resin, styrene resin, polyvinyl chloride or polypropylene.

The first and second mold frames **401** and **402** are disposed at opposite sides of the liquid crystal panel **10** to protect the liquid crystal panel **10**.

In particular, the first and second mold frames **401** and **402** can be disposed at opposite sides of the liquid crystal panel **10**. Thus, the mold frame **400** is not disposed at the other sides of the liquid crystal panel **10**, so that the LCD can have a slim structure.

Although not shown in FIGS. **8** to **10**, a lamp receiving section having a low step difference can be formed at the inner side of the second mold frame **402** such that the lamp receiving section receives a light emitting unit of the backlight unit.

The first and second mold frames **401** and **402** comprise a body section **410** and a receiving section **420**, respectively.

The body section **410** is disposed at the side of the liquid crystal panel **10** while having a first width **T1**. The body section **410** makes contact with the side of the liquid crystal panel **10**.

The receiving section **420** extends from both ends of the body section **410** while having a second width **T2**. For example, the receiving section **420** and the body section **410** can be connected with each other while forming a step difference therebetween. The receiving section **420** is formed with the body section **410** in one united body.

Further, the receiving section **420** is formed such that the corners of the liquid crystal panel **10** are located at the edges of the first and second mold frames **401** and **402**.

The second width **T2** is smaller than the first width **T1**. Thus, the first and second mold frames **401** and **402** can ensure a coupling space when they are coupled with the liquid crystal panel **10**.

In detail, the receiving section **420** can be spaced apart from the liquid crystal panel **10** by the difference between the first width **T1** and the second width **T2**.

Accordingly, when the liquid crystal panel **10** is coupled with the mold frame **400**, the corners of the liquid crystal panel **10** are located at the receiving section **420** of the mold

frame 400, so that the corners of the liquid crystal panel 10 can be prevented from being damaged.

In particular, when manufacturing the liquid crystal panel 10, since burr phenomenon occurs, in which the corners of the liquid crystal panel 10 are not smoothly formed, the liquid crystal panel 10 may be broken when the liquid crystal panel 10 is coupled with the receiving device 60. According to the embodiment, the receiving section 420 is formed at the mold frame 400, so that the liquid crystal panel 10 can be prevented from being broken when the liquid crystal panel 10, in which the burr phenomenon has occurred, is coupled with the mold frame 400.

The chassis 500 is prepared for improving the strength of the mold frame 400 and is coupled with the outer end surface of the mold frame 400.

The chassis 500 may comprise metal material. For example, the chassis 500 may comprise at least one of stainless steel, iron, aluminum, an aluminum alloy and copper.

The chassis 500 comprises a first support section 511 and second support sections 512.

The first support section 511 is disposed below the liquid crystal panel 10 and the mold frame 400. Further, the first support section 511 is prepared for supporting the bottom surface of the mold frame 400 coupled with the liquid crystal panel 10, and has an area corresponding to the lower areas of the liquid crystal panel 10 and the mold frame 400.

The second support sections 512 extend from the first support section 511 upward such that the second support sections 512 are disposed at the sides of the liquid crystal panel 10 and the mold frame 400.

The second support sections 512 are prepared for supporting the sides of the liquid crystal panel 10 and the mold frame 400. For example, the number of the second support sections 512 is four and the second support sections 512 form a rectangular frame.

At this time, the second support sections 512 are disposed at the sides of the liquid crystal panel 10 except for areas corresponding to the corners of the liquid crystal panel 10. Two of the second support sections 512 are disposed at left and right sides of the liquid crystal panel 10 while facing each other.

Further, the other two of the second support sections 512 are disposed at the outer sides of the first and second mold frames 401 and 402 while facing each other.

A third support section 513 is formed at the chassis 500 to improve the strength of the chassis 500.

The third support section 513 extends from the edge of the second support section 512 inward at an angle of more than 150°. According to the embodiment, the third support section 513 extends from the second support section 512 inward at an angle of 180° so that the third support section 513 is parallel to the second support section 512.

In detail, the third support section 513 is subject to hamming such that the third support section 513 is folded while facing the second support section 512. Thus, the second and third support sections 512 and 513 form a double frame structure, so that the strength of the chassis 500 can be improved more than twice.

Further, the third support sections 513 are disposed at the sides of the liquid crystal panel 10 or the mold frame 400.

The third support section 513 may be formed on the entire surface of the second support section 512 or may be formed on a part of the second support section 512.

In particular, the third support sections 513 are selectively formed, so that the strength of the chassis 500 can be improved and the assembly space for the liquid crystal panel 10 can be ensured.

In detail, the third support sections 513 can be formed only remaining portions except for the edges at which the corners of the liquid crystal panel 10 are located.

For example, the third support sections 513 expose the corners of the liquid crystal panel 10.

The second and third support sections 512 and 513 can be classified into a portion that is subject to the hamming, and a portion that is not subject to the hamming.

Thus, the center portion of the second support section 512 is provided with the third support section 513 that is subject to the hamming, so that the strength of the chassis 500 can be improved more than twice.

In addition, since the edge of the second support section 512 has not been subject to the hamming process, the edge has a thickness less than a half of that of the center portion.

Thus, the edges of the second support section 512, at which the corners of the liquid crystal panel 10 are disposed, ensure a wider space than the center portion, so that the corners of the liquid crystal panel 10 can be prevented from being broken when the chassis 500 is coupled with the liquid crystal panel 10.

The corners of the chassis 500 are provided with opening sections 501 formed by removing a part of the chassis 500, so that the chassis 500 can be coupled with the mold frame 400.

As the mold frame 400 is coupled with the chassis 500, the edges of the first and second mold frames 401 and 402, which correspond to the corners of the mold frame 400, are inserted into the opening sections 501 of the chassis 500. Thus, the first and second mold frames 401 and 402 are received in the chassis 500.

Further, when viewed in a plan view, the frames of the mold frame 400 and the chassis 500 form a closed loop. At this time, the mold frame 400 and the second support section 512 can have the same height.

As the liquid crystal panel 10 is coupled with the receiving device formed by coupling the mold frame 400 with the chassis 500, the liquid crystal panel 10 is located between the first and second mold frames 401 and 402. Other sides of the liquid crystal panel 10 face the inner sides of the second support sections 512 of the chassis 500.

In particular, the receiving section 420 is formed at the edges of the first and second mold frames 401 and 402, at which the corners of the liquid crystal panel 10 are located, and the edge of the chassis 500 has a thickness thicker than any other parts to ensure a wider space in the receiving section 420.

Thus, when the liquid crystal panel 10 is coupled with the chassis 500, the corners of the liquid crystal panel 10 are coupled with the wide corners of the receiving section 420, so that the corners of the liquid crystal panel 10 can be prevented from being broken.

Further, the mold frame 400 and the chassis 500 are disposed at opposite sides of the liquid crystal panel 10, and only the chassis 500 is disposed at other sides of the liquid crystal panel 10, so that the LCD can have a slim structure while having improved strength.

Furthermore, in the chassis 500, the third support section 513 extends from the second support section 512. Thus, the chassis 500 has a dual structure and supports the sides of the mold frame 400 and the liquid crystal panel 10, so that the strength of the LCD can be reinforced.

Moreover, the backlight assembly provided with the light emitting unit is coupled with the bottom surface of the liquid crystal panel 10, so that the mold frame 400 and the chassis 500 form a closed loop. Thus, light irradiated from the light emitting unit can be prevented from being leaked.

Hereinafter, a receiving device according to a fourth embodiment will be described with reference to FIGS. 11 and 12.

FIG. 11 is a perspective view illustrating a state in which a liquid crystal panel is coupled with the receiving device according to the fourth embodiment, and FIG. 12 is an enlarged plan view illustrating the area D of FIG. 11.

Referring to FIGS. 11 and 12, the receiving device comprises only a chassis 600. The chassis 600 may comprise metal material. For example, the chassis 600 may comprise at least one of stainless steel, iron, aluminum, an aluminum alloy and copper.

The chassis 600 comprises a first support section 611, second support sections 612 and third support sections 613.

The first support section 611 is disposed below the liquid crystal panel 10 to support the liquid crystal panel 10. The first support section 611 has an area corresponding to the lower area of the liquid crystal panel 10.

The second support sections 612 extend from the first support section 611 in different direction with the first support section such that the second support sections 612 are disposed at the sides of the liquid crystal panel 10. When viewed in a plan view, the second support sections 512 form a rectangular frame.

The third support section 613 extends from the edge of the second support section 612 inward at an angle of more than 150°. According to the embodiment, the third support section 613 extends from the second support section 612 inward at an angle of 180° so that the third support section 613 is parallel to the second support section 512.

In detail, the third support section 613 and the second support section 612 are subject to hamming to be folded such that the third support section 613 faces the second support section 612. Thus, the second and third support sections 612 and 613 form a double frame structure, so that the strength of the chassis 600 can be improved more than twice.

The first to third support sections 611 to 613 are formed in one united body.

The third support sections 613 are selectively formed in areas except for the corners of the chassis 600, so that the strength of the chassis 600 can be improved and the assembly space for the liquid crystal panel 10 can be ensured.

In detail, the third support sections 613 can be formed only in remaining areas except for the corners of the second support sections 612.

In other words, the third support sections 613 expose the corners of the liquid crystal panel 10. Further, the third support sections 613 are connected to the first support section 611 through the second support sections 612.

Thus, the third support sections 613 are bent or curved from the edges of the second support sections 612 through the hamming process except for the corners of the second support sections 612, so that the strength of the chassis 600 can be improved more than twice.

Further, the second support sections 612 are formed in the corners of the chassis 600, but the third support sections 613 not formed.

Thus, the corners of the chassis 600, at which the corners of the liquid crystal panel 10 are disposed, ensure a wider space than the center portion of the chassis 600, so that contact between the corners of the liquid crystal panel 10 and the chassis 600 is minimized when the chassis 600 is coupled with the liquid crystal panel 10. Consequently, the liquid crystal panel 10 can be prevented from being broken.

Further, the second support sections 612 are formed in one united body while forming a closed loop, so that the strength of the chassis 600 can be enhanced.

Hereinafter, a receiving device according to a fifth embodiment will be described with reference to FIGS. 13 and 14.

FIG. 13 is a perspective view illustrating a state in which a liquid crystal panel is coupled with a chassis having opening sections at the corners thereof, and FIG. 14 is an enlarged plan view illustrating the area E of FIG. 13.

The opening sections 701 can be formed in the chassis 700 by removing the corners of the chassis 700.

Since contact areas among the first to fourth frames 210, 220, 230 and 240 of the chassis 700 are removed, the opening sections 701 expose a first support section 711 corresponding to the corners of the chassis 700.

When the liquid crystal panel 10 is coupled with the chassis 700, the sides of the liquid crystal panel 10 are located at the inner sides of third support sections 713.

In particular, since the opening sections 701, from which the second and third support sections 712 and 713 are removed, are formed at the corners of the chassis 700 in which the corners of the liquid crystal panel 10 are located, the corners of the liquid crystal panel 10 do not make contact with the second and third support sections 712 and 713 of the chassis 700 when the liquid crystal panel 10 is coupled with the chassis 700. Thus, the corners of the liquid crystal panel 10 can be prevented from being broken.

Further, the liquid crystal panel 10 is directly coupled with the chassis 700 comprising metal, so that the LCD can have a slim structure.

Furthermore, the third support section 713 selectively subject to hamming is formed at the second support section 712 of the chassis 700, so that the second and third support sections 712 and 713 of the chassis 700 support the liquid crystal panel 10 while forming a dual structure. Thus, the strength of the receiving device can be improved more than twice.

FIG. 15 is a perspective view illustrating a state in which a liquid crystal panel is coupled with a chassis according to a sixth embodiment, and FIG. 16 is an enlarged plan view illustrating the area F of FIG. 15.

Referring to FIGS. 15 and 16, the chassis 800 comprises a first support section 811 and second support sections 812.

The first support section 811 is disposed below the liquid crystal panel 10 and the second support sections 812 are disposed at the sides of the liquid crystal panel 10.

The chassis 800 comprises only the first support section 811 and the second support sections 812. In detail, the chassis 800 according to the embodiment does not comprise the third support sections as described in the embodiments.

Thus, the chassis 800 according to the embodiment supports the sides of the liquid crystal panel 10 using only the second support sections 812, so that the LCD according to the embodiment can have a slim structure.

The opening sections 801 can be formed in the chassis 800 by removing the corners of the chassis 800.

Since the corners of the chassis 800 are removed, the opening sections 801 expose a first support section 811 corresponding to the corners of the chassis 800.

As the liquid crystal panel 10 is coupled with the chassis 800, the second support sections 812 are located at the sides of the liquid crystal panel 10.

In particular, the opening sections 801 are formed at the corners of the chassis 800 in which the corners of the liquid crystal panel 10 are located, so that the corners of the liquid crystal panel 10 can be prevented from being broken when the liquid crystal panel 10 is coupled with the chassis 800.

Further, the liquid crystal panel 10 is directly coupled with the chassis 800 comprising metal, so that the LCD can have a slim structure. In particular, the chassis 800 supports the sides

of the liquid crystal panel **10** using only the second support sections **912**, so that the LCD according to the embodiment can have a slim structure.

FIG. **17** is an exploded perspective view illustrating a receiving device according to a seventh embodiment, FIG. **18** is a plan view illustrating an LCD according to the seventh embodiment, and FIG. **19** is a sectional view taken along line G-G' of FIG. **18**.

Referring to FIGS. **17** to **19**, the LCD comprises the receiving device **70**, the backlight assembly **20** and the liquid crystal panel **10**.

The receiving device **70** receives the backlight assembly **20** and the liquid crystal panel **10**. The receiving device **70** comprises a chassis **910**, a mold frame **920** and impact absorbing members **930**.

The chassis **910** surrounds the mold frame **920**. In detail, the mold frame **920** is disposed at the inner side of the chassis **910**. The chassis **910** and the mold frame **920** can be coupled with each other.

The chassis **910** comprises a first support section **911** and second support sections **912**.

The first support section **911** is disposed below the liquid crystal panel **10**. In more detail, the first support section **911** is disposed below the mold frame **920** to support the mold frame **920**. Further, the first support section **911** is disposed below the backlight assembly **20** to support the backlight assembly **20**.

The second support sections **912** extends vertically from the first support section **911**. The second support sections **912** are disposed at the sides of the liquid crystal panel **10** and/or the backlight assembly **20**. Further, the second support sections **912** are disposed at the outer sides of the mold frame **920**.

When viewed in a plan view, the second support sections **912** form a closed loop. Further, the second support sections **912** support the sides of the mold frame **920**. Furthermore, the second support section **912** has a height of about 0.9 mm to 1.5 mm.

The chassis **910** may comprise metal. For example, the chassis **910** may comprise stainless steel, iron, aluminum, an aluminum alloy, copper, zinc and the like.

The mold frame **920** is disposed at the inner side of the chassis **910** and is disposed on the first support section **911**. The mold frame **920**, for example, comprises four frames to form a rectangular frame. In detail, the mold frame **920** comprises first to fourth frames **921** to **924** formed in one united body.

The first frame **921** faces the third frame **923** and the second frame **922** faces the fourth frame **924**. The mold frame **920** forms a closed loop.

For example, the mold frame **920** may use polystyrene resin, polyethylene resin, polyurethane resin and the like.

The second and fourth frames **922** and **924** have a height **H2** lower than the height **H1** of the second support section **912**, respectively. The second and fourth frames **922** and **924** may have the height **H2** of about 0.4 mm to 0.8 mm. In detail, the second and fourth frames **922** and **924** expose a part of the inner sides of the second support sections **912**.

The first and third frames **921** and **923** may have a height corresponding to the height **H1** of the second support section **912**, respectively. At this time, the first and third frames **921** and **923** have a structure in which a high portion and a lower portion are coupled with each other while forming a step difference therebetween.

The impact absorbing members **930** protect display panels disposed at the inner side of the mold frame **920** from physical impact. The impact absorbing members **930** absorb external

physical impact or vibration. The impact absorbing members **930** are disposed at the inner side of the second support sections **912** while making contact with the second support sections **912**. Further, the impact absorbing members **930** are disposed on the second and fourth frames **922** and **924**.

The impact absorbing members **930** are disposed between the liquid crystal panel **10** and the second support section **912**, respectively.

The impact absorbing member **930** and the second frame **922** may have height **W** and **H2** respectively, wherein the total height of the height **W** and **H2** corresponds to the height **H1** of second support section **912**.

Further, the impact absorbing member **930** can be disposed between the first frame **921** and the liquid crystal panel **10**, and between the third frame **923** and the liquid crystal panel **10**.

The impact absorbing member **930** may use acryl resin, polyurethane resin, rubber resin, tape and the like. The impact absorbing member **930** may comprise black pigment, black dye or black pixel.

The backlight assembly **20** is disposed at the inner side of the receiving device **70**. The backlight assembly **20** generates light to output the light upward. The backlight assembly **20** comprises the reflective sheet **23**, the lamp and the light guide plate **22** and the optical sheets **21**.

The reflective sheet **23** is disposed on the first support section **911** at the inner side of the mold frame **920**. The reflective sheet **23** reflects light, which is generated from the lamp **26**, in the upward direction.

The light guide plate **22** is disposed on the reflective sheet **23**. The light guide plate **22** is disposed at the inner side of the mold frame **920**. The light guide plate **22** diffuses the light, which is generated from the lamp **26**, in the upward direction.

The lamp **26** is disposed at the inner side of the mold frame **920** while being disposed on the reflective sheet **23**. Further, the lamp **26** is disposed at the side of the light guide plate **22**. The lamp **26** generates the light.

The optical sheets **21** are disposed on the light guide plate **22** while being disposed at the inner side of the mold frame **920**. The optical sheets **21** improve the properties of the light generated from the lamp **26**.

The liquid crystal panel **10** is disposed on the optical sheets **21**. The liquid crystal panel **10** is disposed on the second and fourth frames **922** and **924** while being disposed at the inner side of the chassis **910**. The liquid crystal panel **10** comprises a TFT substrate having a plurality of thin film transistors, a color filter substrate having color filters, and a liquid crystal layer interposed between the TFT substrate and the color filter substrate.

Light blocking members **11** can be disposed at the sides of the liquid crystal panel **10**. The light blocking members **11** can be located adjacent to the liquid crystal panel **10**. Further, the light blocking members **11** can be located adjacent to the impact absorbing member **930**, respectively. The light blocking members **11** are disposed on the mold frame **920** while being disposed at the inner side of the second support section **912**. The light blocking members **11** block light leaked through the sides of the liquid crystal panel **10**.

For example, the light blocking members **11** may comprise acryl resin containing black pigment, black dye or black material.

The liquid crystal panel **10** is disposed on the stepped portion between the first and third frames **921** and **923** of the mold frame **920**, and the second and fourth frames **922** and **924**. According to the seventh embodiment, the ratio of the surface area of the liquid crystal panel **10** with respect to the surface area of the LCD can be increased.

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As compared to the case in which the liquid crystal panel 10 is disposed at the inner side of the mold frame, the surface area of a portion, except for the liquid crystal panel 10, is decreased when viewed in a plan view. In detail, in the LCD according to the seventh embodiment, an area of a portion, in which an image is not displayed, is decreased when viewed in a plan view.

Further, when the chassis 910 comprises metal, physical impact may be applied to the liquid crystal panel 10. At this time, the impact absorbing members 930 protect the liquid crystal panel 10 from physical impact and vibration transferred through the chassis 910.

FIG. 20 is a plan view illustrating an LCD according to an eighth embodiment and FIG. 21 is a sectional view taken along line I-I' of FIG. 20. A description about the eighth embodiment will be given with reference to the seventh embodiment, and a light blocking and impact absorbing member will be additionally described.

The LCD comprises the light blocking and impact absorbing member 940.

The light blocking and impact absorbing member 940 makes contact with the second support section 912. The light blocking and impact absorbing member 940 blocks light leaked through the side of the liquid crystal panel 10 and protects the liquid crystal panel 10 from external physical impact.

In detail, the light blocking and impact absorbing member 940 performs all functions of a light blocking member and an impact absorbing member. The light blocking and impact absorbing member 940 absorbs external physical impact and vibration. The light blocking and impact absorbing member 940 makes contact with the side of the liquid crystal panel 10.

The light blocking and impact absorbing member 940, for example, comprises at least one of black pigment, black dye and black material. The light blocking and impact absorbing member 940 may comprise polyurethane resin, polyrubber resin and the like.

The light blocking and impact absorbing member 940 comprises four members integrally formed with each other to form a closed loop. Further, the light blocking and impact absorbing member 940 is disposed at the side of the liquid crystal panel 10 while making contact with the side of the liquid crystal panel 10. In more detail, the light blocking and impact absorbing member 940 surrounds the side of the liquid crystal panel 10.

The light blocking and impact absorbing member 940 makes contact with the first and third frames 921 and 923, and is disposed on the second and fourth frames 922 and 924 while making contact with the second support section 912.

The LCD provided with the light blocking and impact absorbing member 940 does not require a light blocking member and an impact absorbing member as individual parts. This is because the light blocking and impact absorbing member 940 performs all functions of the light blocking member

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and the impact absorbing member. Thus, the surface area of a portion, in which an image is not displayed, can be decreased.

Although embodiments have been described with reference to a number of illustrative embodiments thereof, it should be understood that numerous other modifications and embodiments can be devised by those skilled in the art that will fall within the spirit and scope of the principles of this disclosure. More particularly, various variations and modifications are possible in the component parts and/or arrangements of the subject combination arrangement within the scope of the disclosure, the drawings and the appended claims. In addition to variations and modifications in the component parts and/or arrangements, alternative uses will also be apparent to those skilled in the art.

INDUSTRIAL APPLICABILITY

The display devices according to the embodiments are applied to a display module.

What is claimed is:

1. A display device comprising:

a liquid crystal panel;

a backlight assembly disposed below the liquid crystal panel;

a chassis including:

a first support section, which is disposed at sides of the liquid crystal panel and the backlight assembly, and a second support section, which is bent or curved from the first support section; and

a frame disposed at an inner side of the chassis, wherein the frame has a first frame, a second frame, a third frame and a fourth frame and at least one of the first to the fourth frames has a height lower than a height of the first support section.

2. The display device of claim 1, further comprising an impact absorbing member interposed between the liquid crystal panel and the first support section to absorb impact and vibration.

3. The display device of claim 2, wherein the impact absorbing member includes at least one of acryl resin, polyurethane resin, rubber resin, a tape, black pigment, black dye and black material.

4. The display device of claim 2, wherein the impact absorbing member is disposed on the second and fourth frames.

5. The display device of claim 1, wherein the first frame faces the third frame and the second frame faces the fourth frame.

6. The display device of claim 1, wherein the second and fourth frames have a height lower than the height of the second support section.

7. The display device of claim 1, wherein the second and fourth frames have a height of 0.4 mm to 0.8 mm.

* * * * *

Fig. 2

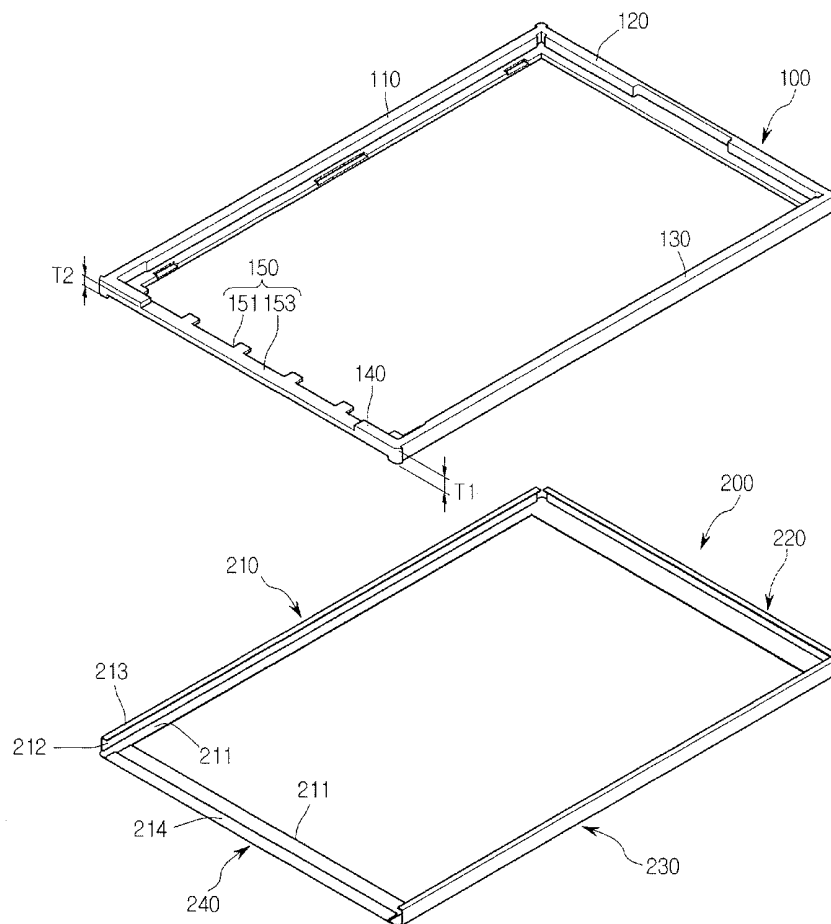


Fig. 3

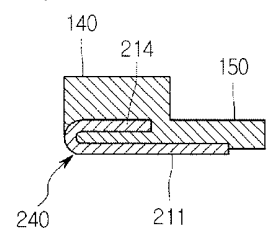


Fig. 4

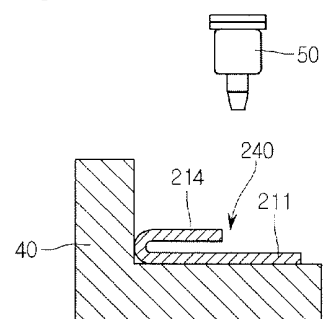


Fig. 5

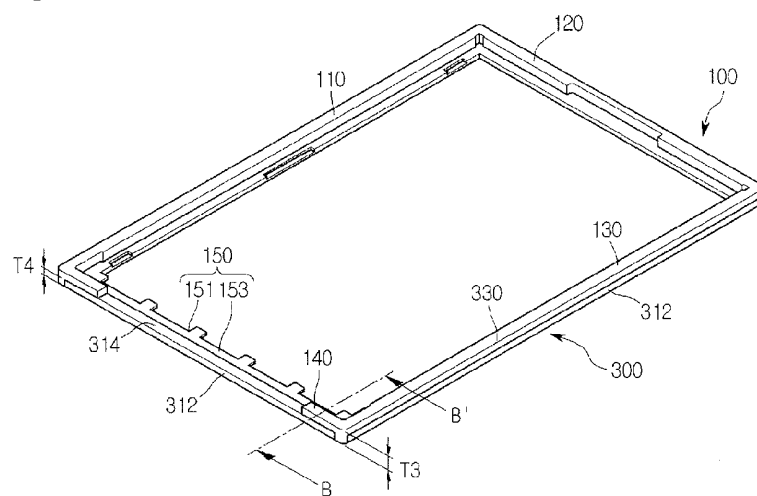


Fig. 6

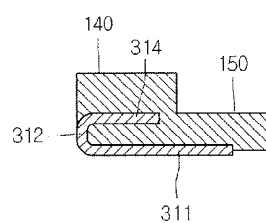


Fig. 7

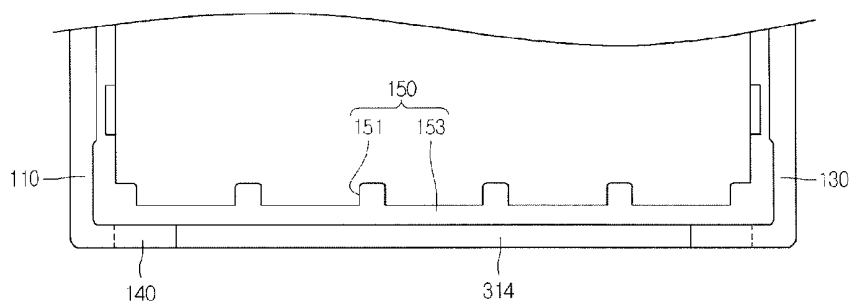


Fig. 8

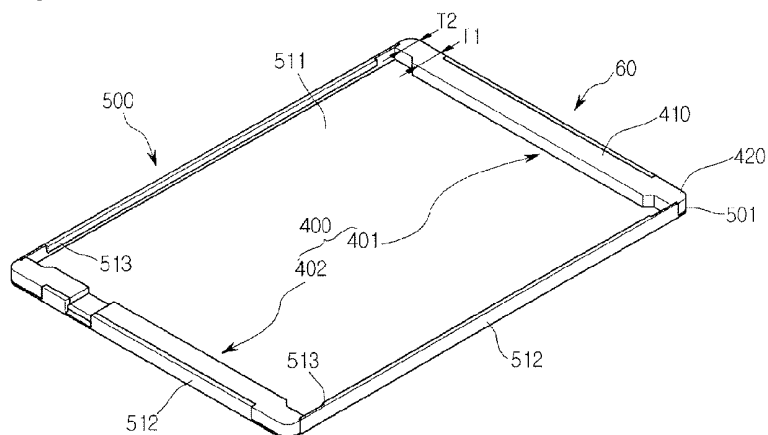


Fig. 9

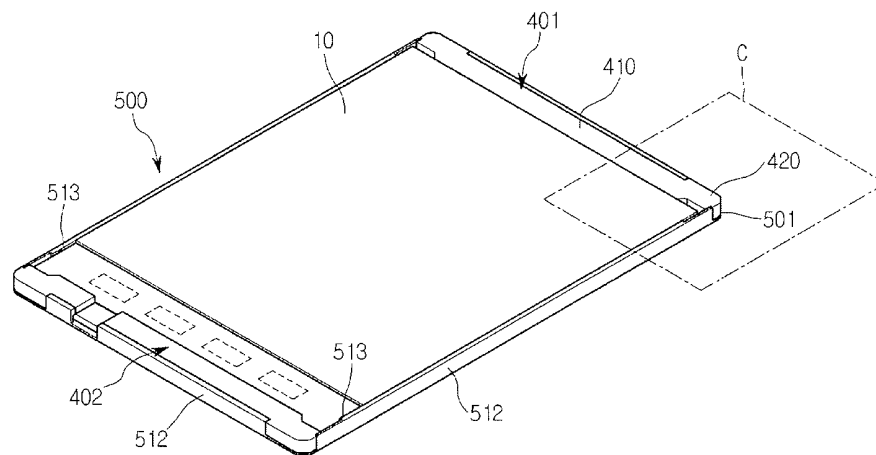


Fig. 10

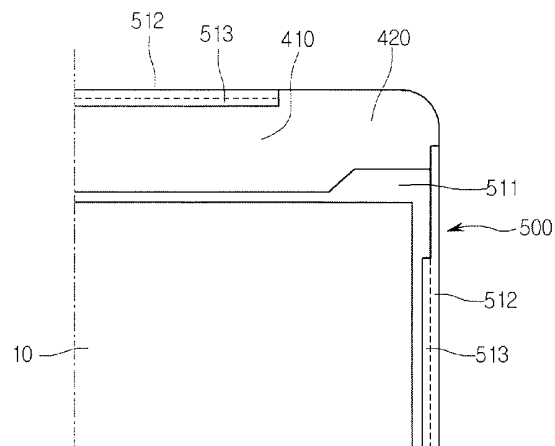


Fig. 11

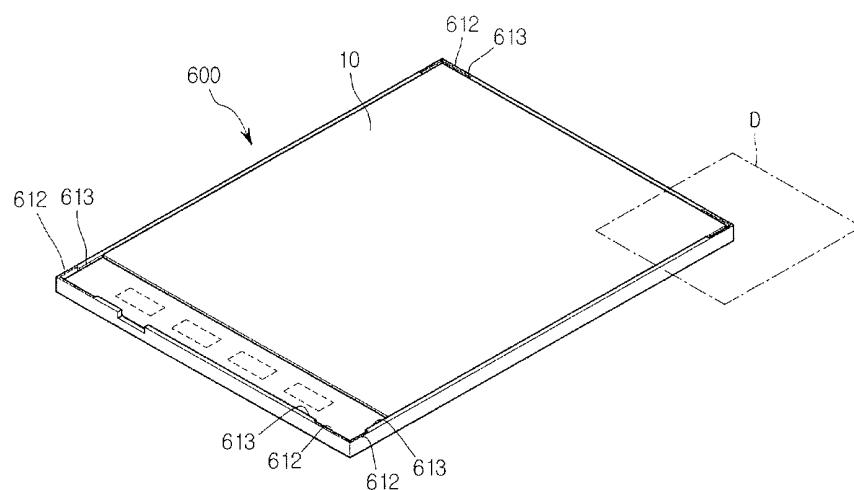


Fig. 12

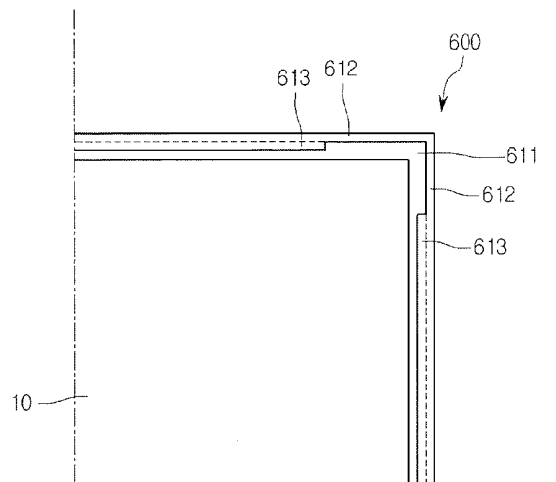


Fig. 13

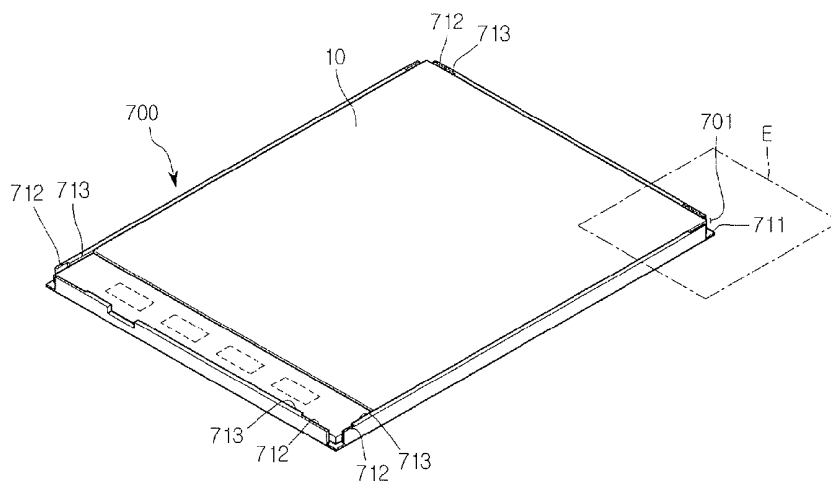


Fig. 14

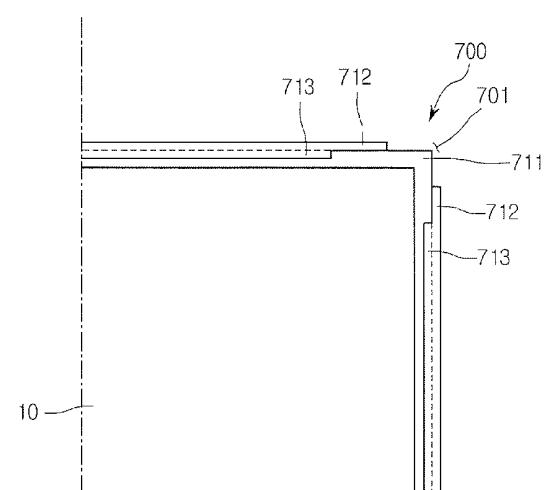


Fig. 15

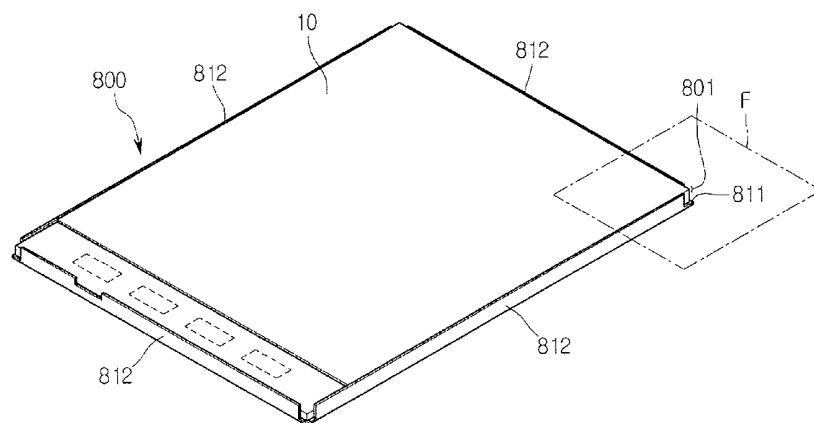


Fig. 16

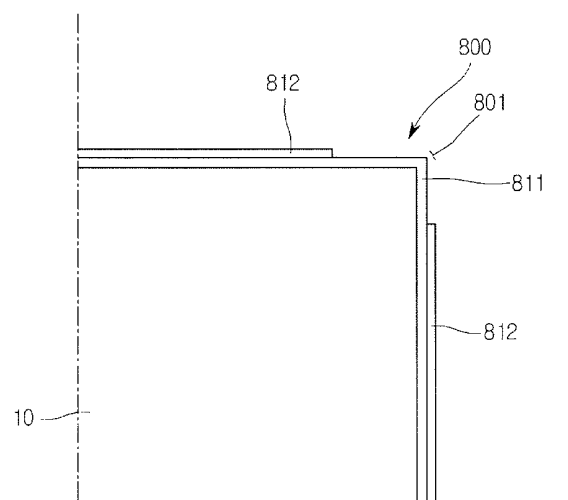


Fig. 17

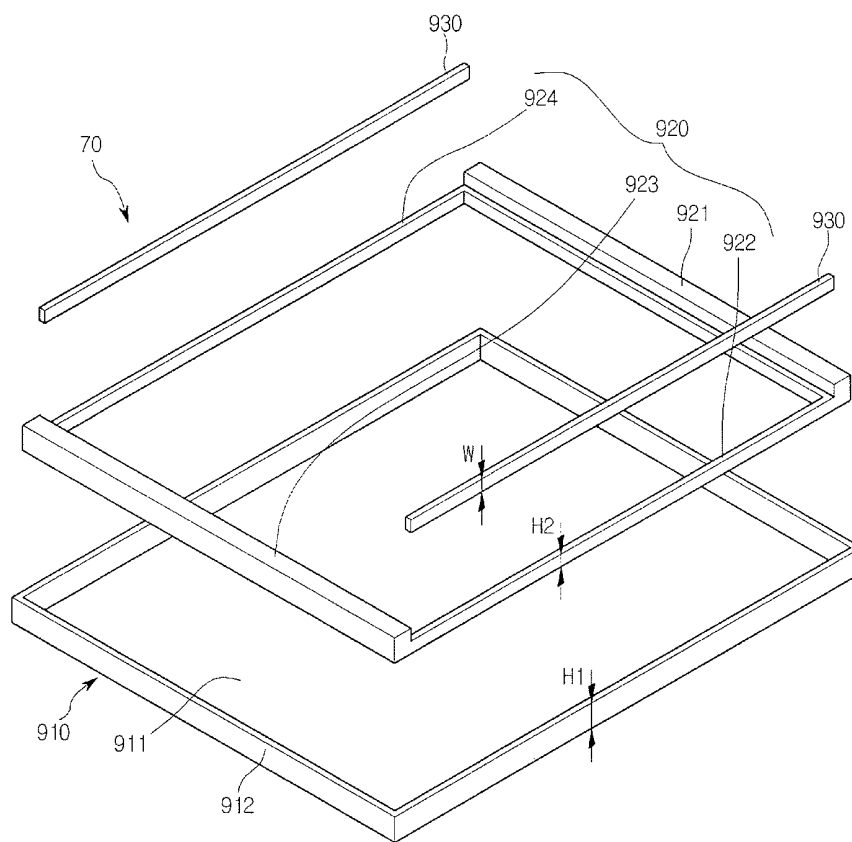


Fig. 18

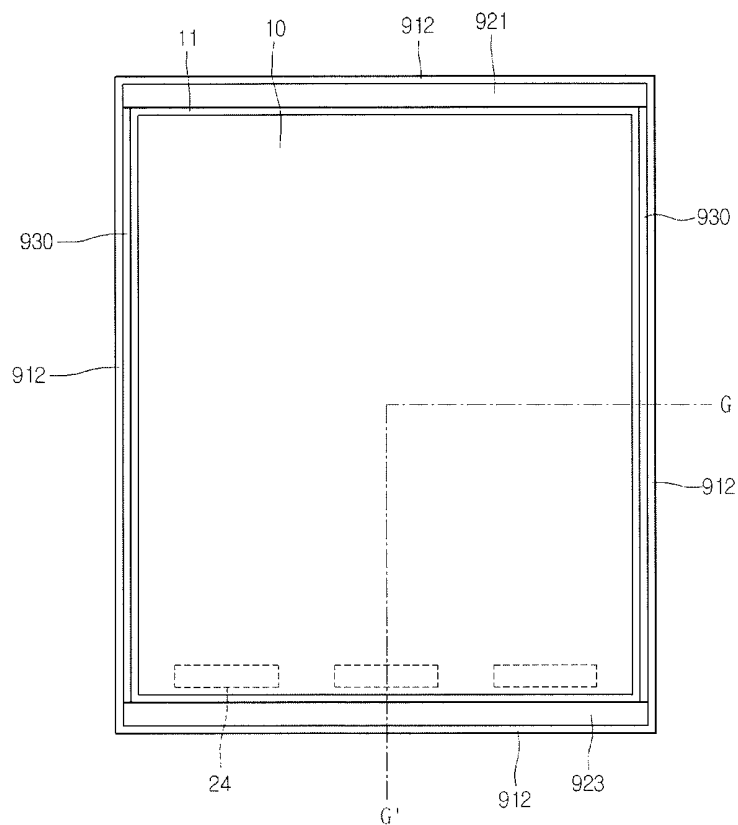


Fig. 19

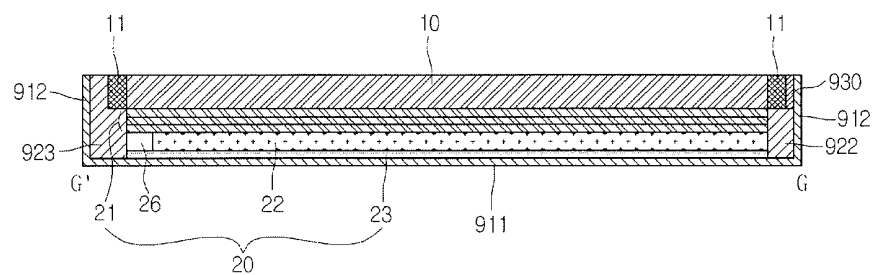


Fig. 20

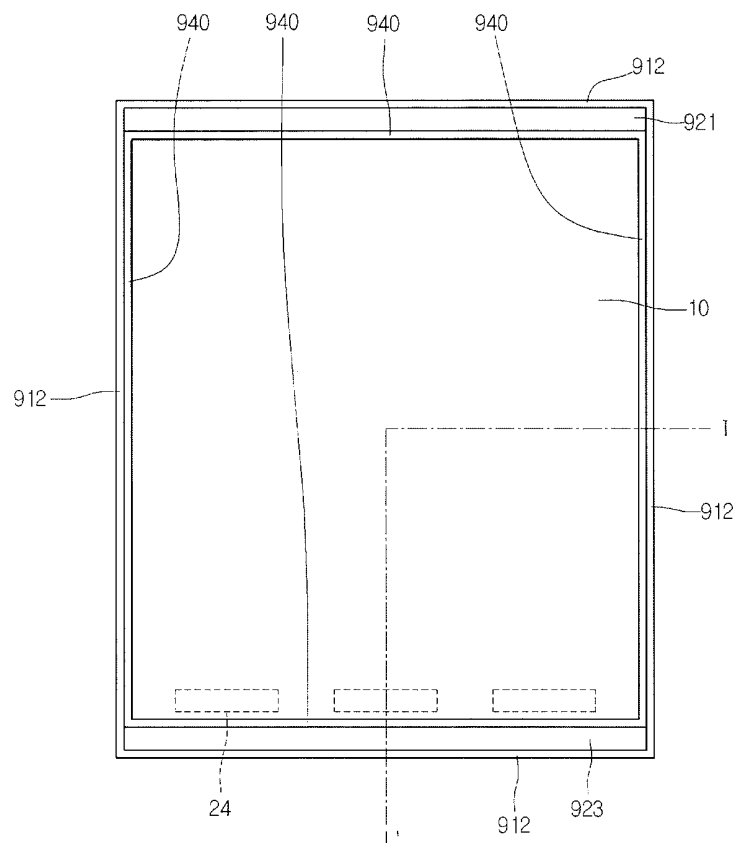
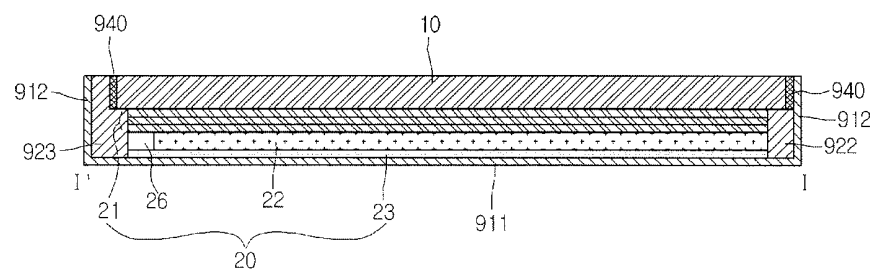


Fig. 21



专利名称(译)	显示设备		
公开(公告)号	US8467011	公开(公告)日	2013-06-18
申请号	US13/720930	申请日	2012-12-19
[标]申请(专利权)人(译)	乐金显示有限公司		
申请(专利权)人(译)	LG DISPLAY CO. , LTD. ,		
当前申请(专利权)人(译)	LG DISPLAY CO. , LTD.		
[标]发明人	CHOI HYUN HO KIM HAN YOUNG		
发明人	CHOI, HYUN HO KIM, HAN YOUNG		
IPC分类号	G02F1/1333		
CPC分类号	G02B6/0088 G02B6/0093 G02F1/133308 G02F1/133608 G02F2001/133314		
代理机构(译)	桦木， STEWART， KOLASCH与桦木， LLP		
优先权	1020070072680 2007-07-20 KR 1020070067994 2007-07-06 KR 1020070069895 2007-07-12 KR PCT/KR2008/003877 2008-07-01 WO		
其他公开文献	US20130107162A1		
外部链接	Espacenet USPTO		

摘要(译)

根据实施例的显示装置包括液晶面板;背光组件，设置在液晶面板下方;底盘包括：第一支撑部分，设置在液晶面板和背光组件的侧面;以及第二支撑部分，从第一支撑部分弯曲或弯曲;框架设置在底盘的内侧，其中框架具有第一框架，第二框架，第三框架和第四框架，并且第一框架至第四框架中的至少一个具有低于高度的高度第一个支持部分。

